electronic circuit board 7 electrically connected to the optical semiconductor element module 6 and having pads 8a and 8b on its surface; an electrically conductive casing 9 in the form of, e.g., a sheet metal box, which accommodates and electromagnetically shields the electronic circuit board 7; and a metal flange 10 interposed between the optical semiconductor element module 6 and the electrically conductive casing 9, a metal flange 10 being fitted with the optical semiconductor module 6 and fixedly secured to the electrically conductive casing 9 by means of screws 11a and 11b. The optical semiconductor element module 6 includes a stem 1 incorporating an optical semiconductor element; lead terminals 2a and 2b extending from the stem 1 for electrical connection with the optical semiconductor element; a can 3 partially covering the stem 1; a trunk 4 extending from the can 3; and a fiber 5 disposed on the trunk 4.

Please replace the paragraph beginning at page 2, line 11 with the following:

A conventional optical transmitter/receiver can be configured in the manner of the optical transmitter/receiver 900 described in the following. The electronic circuit board 7 is securely retained, for example by an adhesive, in the electrically conductive casing 9. The optical semiconductor element module 6 and the metal flange 10 are fixedly retained, for example by YAG welding. The electrically conductive casing 9 and the metal flange 10 are fastened together by screws or the like. The lead terminals 2a and 2b are connected to the pads 8a and 8b, respectively, for transmission/reception and conversion of optical /electric signals.

Please replace the paragraph beginning at page 16, line 8, with the following:

The optical transmitter/receiver 200 is configured in this manner. With the slits 16a, 16b and the protrusions 18a, 18b provided in and on the sidewalls of the resin flange 12 of the first embodiment, the resin flange 12 is fitted slidably on the electrically conductive casing 9 from above such that the slits 16 and 16b can mate with front faces 15a and 15b, respectively, of the electrically conductive casing 9. At this point, the protrusions 18a and 18b initially spread the right and left sidewalls of the electrically conductive casing 9 outward within the range of elastic deformation thereof. When the protrusions 18a and 18b snap into the apertures 17a and 17b formed in the right and left sidewalls, the elastic deformation of the right and left walls of the electrically conductive casing 9 is removed so that the resin flange can fixedly be clamped by the electrically conductive casing 9. As a result, it is possible to remove the screwing or adhesion step required for firmly fastening the electrically conductive casing 9 and the resin flange 12.

IN THE CLAIMS:

Please cancel claims 2, 3, 7, 9 and 16 without prejudice, replace claims 1, 17-19 and add new claim 20 as follows:

1. (Amended) An electronic apparatus comprising:

an electronic circuit board;

an electrically conductive casing for encasing said electronic circuit board;

a semiconductor element module electrically connected to said electronic circuit board via a plurality of lead terminals, said semiconductor element module having a